

### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Built-in strain relief, ideal for automated placement
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed  
250°C/10 seconds at terminals

### Mechanical Data

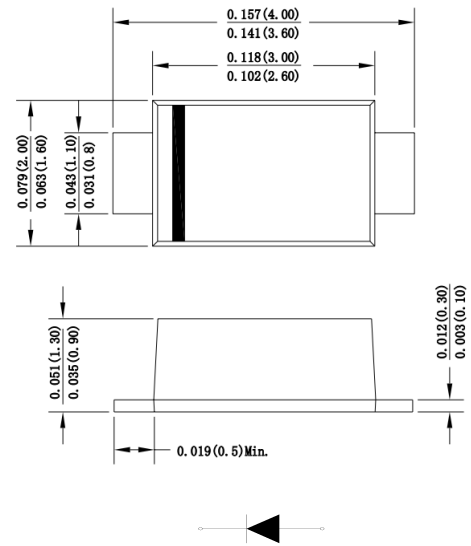
**Case** : Molded plastic body

**Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity** : Polarity symbol marking on body

**Mounting Position** : Any

**Weight** : 0.0007 ounce, 0.02 grams



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	DSK12	DSK14	DSK16	DSK18	DSK110	DSK115	DSK120	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	40	60	80	100	150	200	V
Maximum RMS voltage	$V_{RMS}$	14	28	42	56	70	105	140	V
Maximum DC blocking voltage	$V_{DC}$	20	40	60	80	100	150	200	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	1.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	30.0							A
Maximum instantaneous forward voltage at 1.0A	$V_F$	0.55	0.70	0.85	0.95				V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	$I_R$	0.5 50			0.05 10			mA	
Typical thermal resistance	$R_{qJA}$	85.0							$^\circ\text{C/W}$
Operating junction temperature range	$T_J$	-55 to +125			-55 to +150				$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150							$^\circ\text{C}$

**Ratings And Characteristic Curves**

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

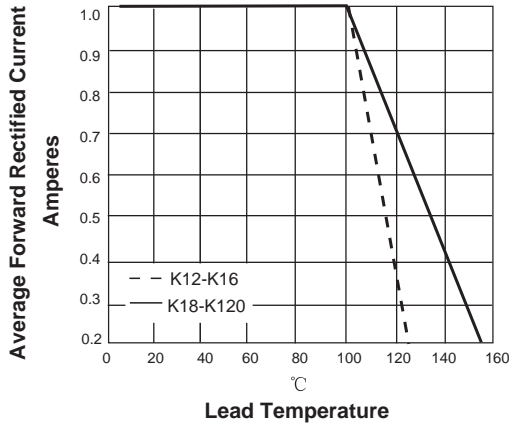


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

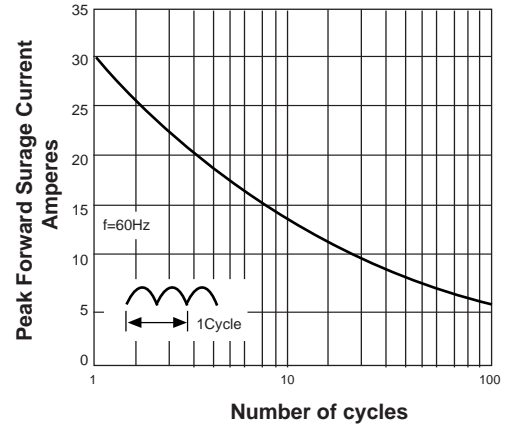


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

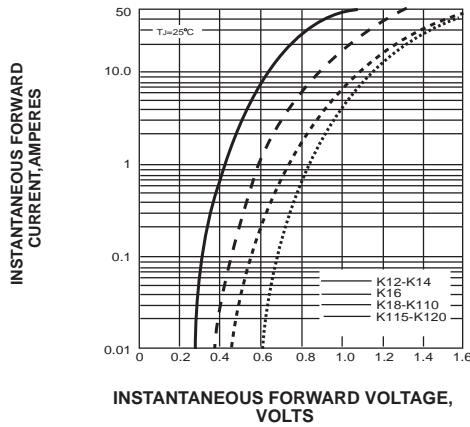
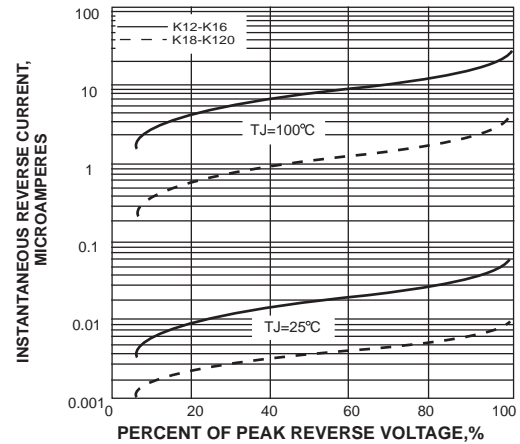
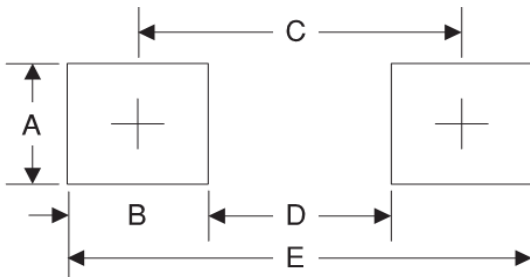


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



**Suggested Pad Layout**



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.048
B	1.15	0.045
C	3.10	0.122
D	1.95	0.077
E	4.25	0.167

### Suggested Soldering Temperature Profile

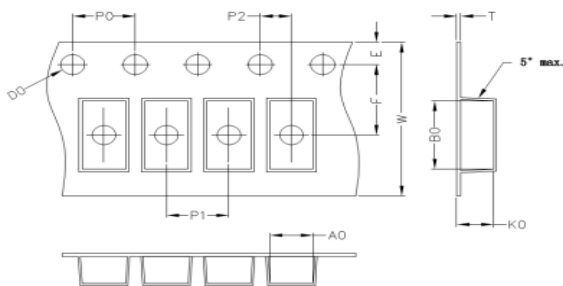


#### Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

### Package Information

#### Carrier Dimension(mm)



<b>A0</b>	<b>B0</b>	<b>K0</b>	<b>D0</b>	<b>E</b>	<b>F</b>
2.15	3.95	1.35	1.55	1.75	3.50
<b>P0</b>	<b>P1</b>	<b>P2</b>	<b>T</b>	<b>W</b>	<b>Tolerance</b>
4.0	4.0	2.0	0.25	8	0.1

#### Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SOD123FL	7'	178	3	180	15	380*200*200	150